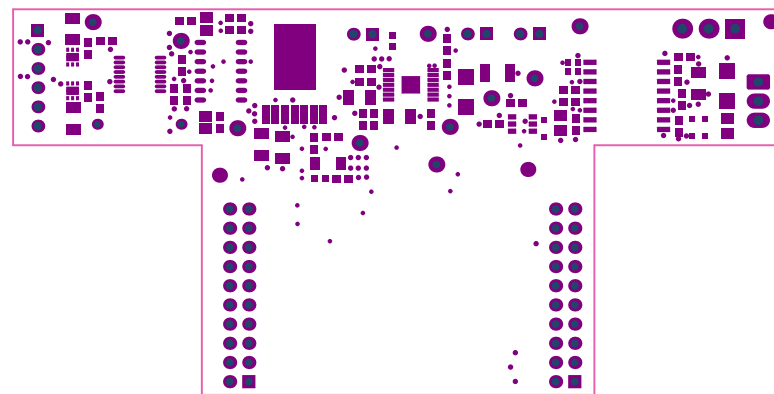
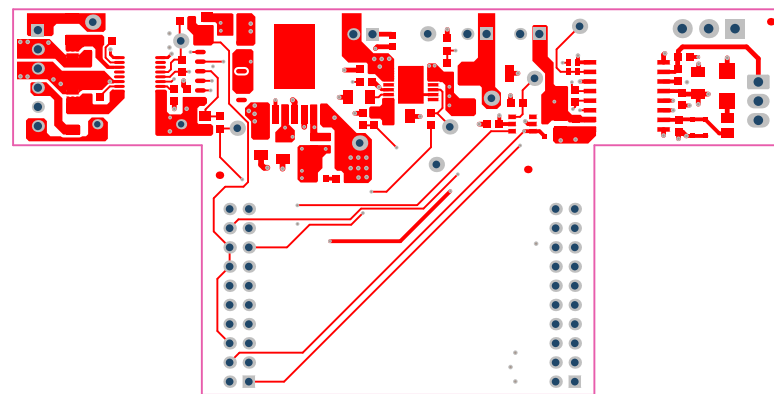


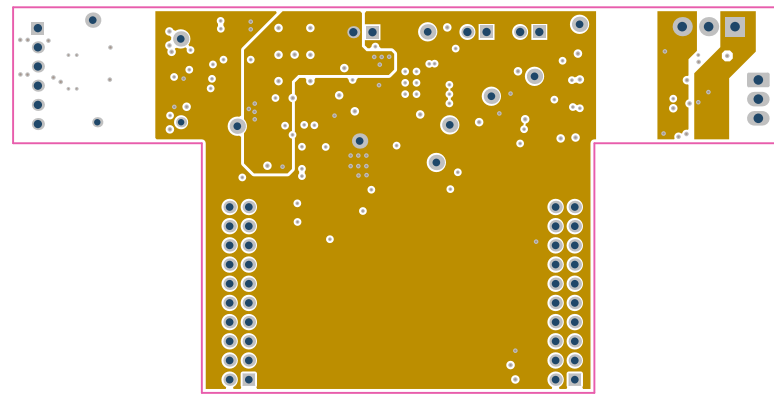
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01599		
PLOT NAME = Top Overlay	GENERATED : 11/28/2017 12:12:13 PM		TEXAS INSTRUMENTS



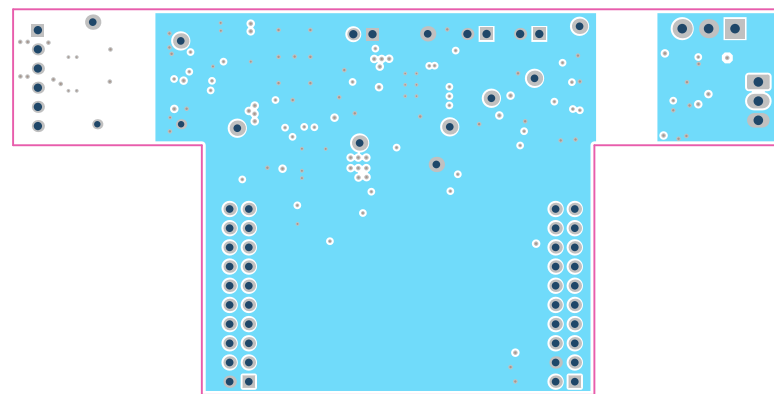
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01599		
PLOT NAME = Top Solder Mask	GENERATED : 11/28/2017 12:12:14 PM		TEXAS INSTRUMENTS



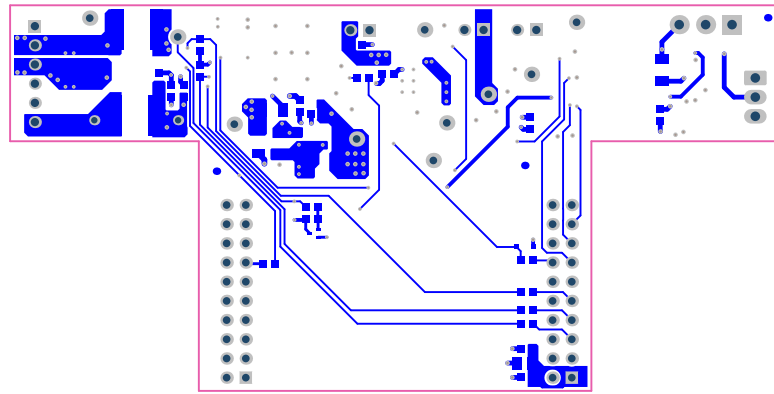
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01599		
PLOT NAME = Top Layer	GENERATED : 11/28/2017 12:12:15 PM		TEXAS INSTRUMENTS



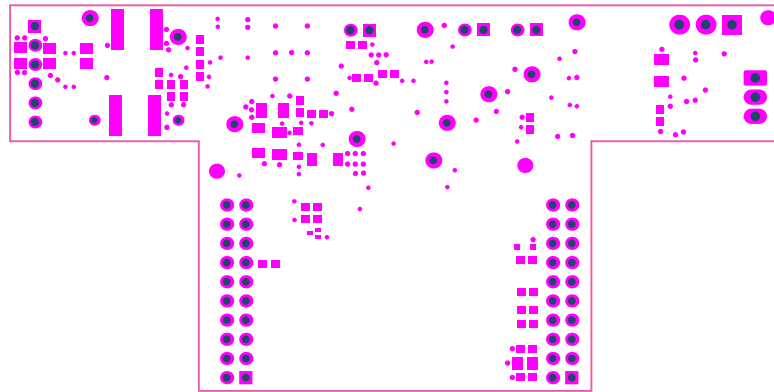
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = POWER	TID #: 01599		
PLOT NAME = Signal Layer 1	GENERATED : 11/28/2017 12:12:16 PM	TEXAS INSTRUMENTS	



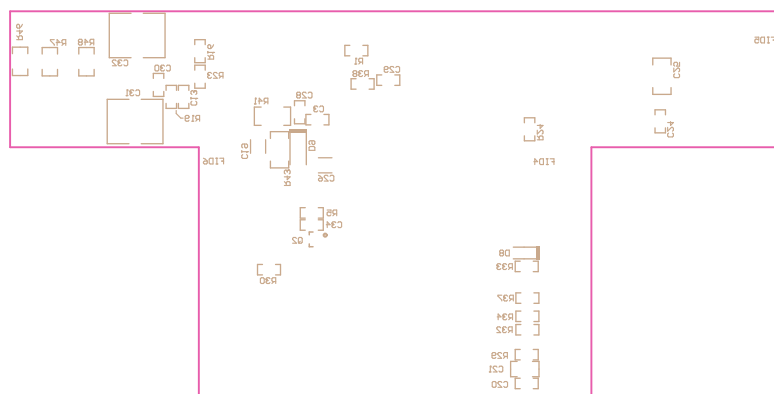
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = GROUND	TID #: 01599		
PLOT NAME = Signal Layer 2	GENERATED : 11/28/2017 12:12:16 PM	TEXAS INSTRUMENTS	



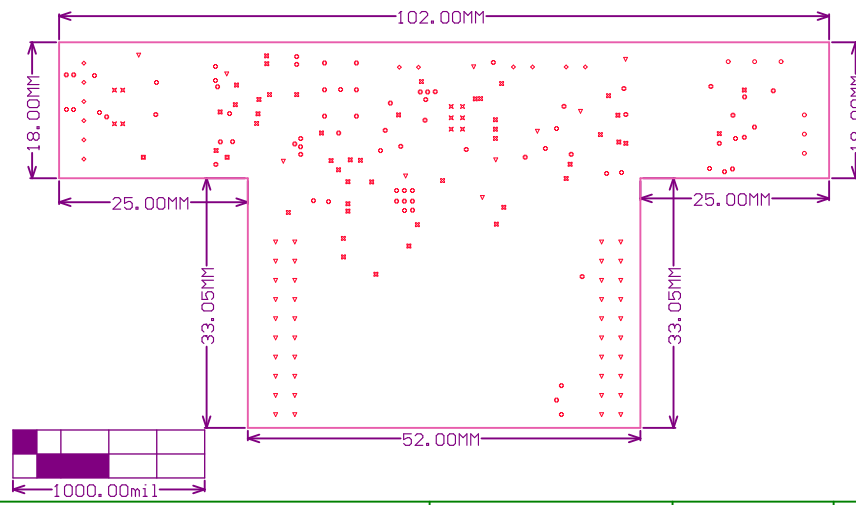
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01599		
PLOT NAME = Bottom Layer	GENERATED : 11/28/2017 12:12:17 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01599		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/28/2017 12:12:18 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01599		
PLOT NAME = Bottom Overlay	GENERATED : 11/28/2017 12:12:19 PM	TEXAS INSTRUMENTS	



Drill Table:

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
⌘	10	7.87mil (0.200mm)	PTH	Round	Via
⊗	46	10.00mil (0.254mm)	PTH	Round	Via
⊕	75	12.00mil (0.305mm)	PTH	Round	Via
■	2	33.46mil (0.850mm)	PTH	Round	Pad
▽	50	40.00mil (1.016mm)	PTH	Round	Pad
◇	12	43.31mil (1.100mm)	PTH	Round	Pad
○	6	50.00mil (1.270mm)	PTH	Round	Pad
	201 Total				

Tolerance:
 For 7.87mil Via +0/-7.87mil
 For 10mil Via +0/-10 mil
 For 12mil Via +0/-12 mil
 For PTH drills +/-3 mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01599	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01599		
PLOT NAME = Drill Drawing	GENERATED : 11/28/2017 12:12:20 PM	TEXAS INSTRUMENTS	

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